



MEG01-004

Application no. 09/837,007

TBW 2891

December 19, 2005

TO: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Attn: Art Unit 2827 - Examiner David A Zarneke

FROM: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 09/837,007
File Date: April 18, 2001
Inventor: M.S. Lin, et al.
Examiner: David A Zarneke
Art Unit: 2891
Title: A Structure and Manufacturing Method of a Chip Scale
Package

RESPONSE TO OFFICE ACTION

Dear Sir:

The Office Action mailed Nov. 18, 2005 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on Dec. 19, 2005.

Signature 
Stephen B. Ackerman, Reg. No. 37,761

Date: Dec. 19, 2005

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 5 of this paper.